



Material Content Data Sheet



Sales Product Name		IFX007T		Issued		1. August 2018		
MA#		MA002167816						
Package		PG-TO263-7-1		Weight*		1534.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.086	0.27	0.27	2663	2663
chip_2	inorganic material	silicon	7440-21-3	1.916	0.12	0.12	1249	1249
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	790	790
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
wire	non noble metal	copper	7440-50-8	808.613	52.71	52.78	527031	527717
	non noble metal	aluminium	7429-90-5	6.772	0.44	0.44	4414	4414
encapsulation	organic material	carbon black	1333-86-4	8.783	0.57		5725	
	plastics	epoxy resin	-	96.614	6.30		62971	
leadfinish	inorganic material	silicondioxide	60676-86-0	480.143	31.29	38.16	312944	381640
	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8497	8497
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.106	0.01		69	
	noble metal	silver	7440-22-4	0.133	0.01		86	
glue	non noble metal	lead	7439-92-1	5.069	0.33	0.35	3304	3459
	plastics	Polyimide	26023-21-2	0.179	0.01	0.01	117	117
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
*deviation	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69225	69315
	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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